

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1.(original) Smart card including a microcircuit, one or more other components, including an accessible component, and external contacts in a card support, characterized in that the microcircuit (1), the accessible component (2) and the external contacts (12) form part of a subassembly (S1, S2) fixed in a housing (C1+C2+C3) formed in a portion of the thickness of the card support, that subassembly including a support film (10) carrying on an internal face the microcircuit (1) and at least the accessible component (2) and on an external face the external contacts (12), a window being formed in the support film facing a portion of the accessible component.

2.(original) Smart card according to Claim 1, characterized in that the subassembly further includes an interface component (3) connected between the microcircuit (1) and the accessible component (2).

3.(original) Smart card according to Claim 2, characterized in that the interface component is a controller for the accessible component.

4.(currently amended) Smart card according to ~~any one of Claims 1 to 3~~ claim 1, characterized in that the connections within the subassembly are made by connecting wires (7, 8, 9).

5.(original) Smart card according to Claim 4, charac-

terized in that each connecting wire is connected, firstly, to the microcircuit (1) or to a component (2, 3), and, secondly, to a connecting track (4, 5) carried by the support film.

6. (currently amended) Smart card according to ~~any one of Claims 1 to 5~~ claim 1, characterized in that the housing includes at least one cavity (C1) in which the microcircuit (1) is fixed and one cavity (C2) in which the accessible component (2) is fixed, at least one rib (15, 16) being provided between the cavities.

7. (original) Smart card according to Claim 6, characterized in that the support film includes an area mechanically weakened in bending between at least the microcircuit and a component and adapted to bear against a rib.

8. (original) Smart card according to Claim 7, characterized in that a mechanically weakened area is formed on either side of the microcircuit and of each component.

9. (currently amended) Smart card according to Claim 7 ~~or Claim 8~~, characterized in that each mechanically weakened area includes at least one slot (F1 to F6).

10. (currently amended) Smart card according to ~~any one of Claims 6 to 9~~ claim 6, characterized in that connecting tracks (4, 5) are formed between the microcircuit and each component, each track facing a rib and being crossed by at least one mechanically weakened area.

11. (currently amended) Smart card according to ~~any one of Claims 6 to 10~~ claim 6, characterized in that each cavity is filled with a rigid material containing the microcircuit or a component and extending as far as the support film.

12.(original) Smart card according to Claim 9, characterized in that each cavity is provided at the periphery of its bottom with at least one depression (18).

13.(original) Method of fabricating a smart card including a microcircuit and at least one other component including an accessible component, the method including the following steps:

- assembling a subassembly (S1 or S2) by mounting on a support film (10) the microcircuit (1) and at least the accessible component (2), providing in the film a window (11) for access to the accessible component, and making the connections by means of connecting wires,
- forming a housing (C1+C2+C3) in the card support,
- fixing the subassembly in the housing.

14.(original) Method according to Claim 13, characterized in that a cavity (C1) for the microcircuit (1) and a cavity (C2) for the accessible component (2) are formed in the housing.

15.(original) Method according to Claim 14, characterized in that areas mechanically weakened in bending (F2, F3, F4, F5) are formed in the support film at least between the microcircuit and the accessible component.

16.(original) Method according to Claim 15, characterized in that areas mechanically weakened in bending are formed in the support film on either side of the microcircuit and of each component.

17.(currently amended) Method according to Claim 15 ~~or~~

~~Claim 16~~, characterized in that the areas mechanically weakened in bending are formed by slots (F1, ..., F6).

18. (currently amended) Method according to ~~any one of Claims 14 to 17~~ claim 14, characterized in that at least one area mechanically weakened in bending is disposed facing a rib (15, 16) formed in the housing between two cavities.

19. (currently amended) Method according to ~~any one of Claims 14 to 18~~ claim 14, characterized in that connecting tracks (4, 5) connected by wires to the microcircuit or to a component are crossed by the areas mechanically weakened in bending.

20. (currently amended) Method according to ~~any one of Claims 14 to 19~~ claim 14, characterized in that at least one depression (18) is formed at the periphery of the bottom of at least one cavity.